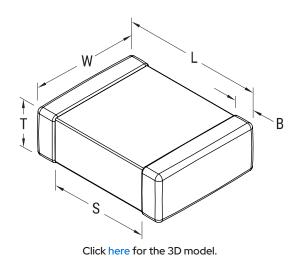


C0603C332K3GECTU

Aliases (C0603C332K3GEC7867) ESD SMD Comm COG, Ceramic, 3,300 pF, 10%, 25 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0603, 0.5 mm



General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	3.7 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.07mm
S	0.5mm MIN
В	0.35mm +/-0.15mm

Packaging Quantity

W	0.8mm +/-0.15mm	Toleran
Т	0.8mm +/-0.07mm	Voltage
S	0.5mm MIN	ESD Lev
В	0.35mm +/-0.15mm	Dielectr
		Temper
Packaging Specifications		Temp. C
Packaging	T&R, 180mm, Paper Tape	Canacit

4000

Specifications	
Capacitance	3,300 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	25 VDC
ESD Level per AEC-Q200	16,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and
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